IN THE CLAIMS

Claim 1 **(currently amended).** An adhesive sheet ~~**composed**~~ **formed of an adhesive system comprising** ~~**of**~~ a mixture of two thermoplastics T1 and T2, wherein **the adhesive system has**

a) ~~**the adhesive system has**~~ a softening temperature of greater than 65°C and less than 125°C,

b) a storage modulus G' at 23°C, as measured by test method A, of greater than 10^7 Pas,

c) a loss modulus G" at 23°C, as measured by test method A, of greater than 10^6 Pas,

d) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 **(currently amended).** The adhesive sheet of claim 1, ~~**characterized in that**~~ **wherein** the layer thickness is between 10 and 100 µm~~**, with particular preference between 30 and 80 µm**~~.

Claim 3 **(currently amended).** The adhesive sheet of ~~**at least one of the preceding claims, characterized in that**~~ **claim 1, wherein** thermoplastics T1 and T2 are selected from the ~~**groups**~~ **group** consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 **(currently amended).** The adhesive sheet of ~~**at least one of the preceding claims, characterized in that reactive resins used additionally comprise**~~ **claim 1, wherein said adhesive system further comprises reactive resins selected from the group consisting of** epoxy resins, ~~**and/or**~~ phenolic resins ~~**and/or**~~ novolak resins **and combinations thereof**.

Claim 5 **(currently amended).** ~~**The use of an adhesive sheet of any one of the above claims**~~ **A method** for bonding chip modules in card bodies **which comprises bonding said chip modules in said card bodies with the adhesive sheet of claim 1**.

Claim 6 **(currently amended).** The ~~use of an adhesive sheet of any one of the above claims for bonding~~ **method of claim 5, wherein said chip modules are** polyimide-, polyester or epoxy-based chip modules and ~~on~~ **said card bodies are** PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 **(currently amended).** A method for producing a heat-activable adhesive tape, ~~characterized in that an~~ **which comprises coating the** adhesive sheet of ~~claims 1 to 4 is coated~~ **claim 1** onto a release paper or a release film.

Claim ~~6~~ **8** (currently amended). The method of claim 7, ~~characterized in that~~ **wherein** the heat-activable adhesive tape is die-cut.

Claim ~~7~~ **9** **(currently amended).** ~~The method of at least one of the preceding claims, characterized in that the heat-activable adhesive tape is processed with~~ **A method for implanting a chip module in a card body, which comprises implanting said chip module in said card body with a heat activable adhesive tape comprised of the adhesive sheet of claim 1 coated onto a release paper or release film, and an implanter having an implanting die at** an implanting die temperature of 150°C.

Claim 10 (new). The adhesive sheet of claim 2, wherein said layer thickness is between 30 and 80 µm.